

Amendments to the Specification

In the paragraph on page 16, beginning at line 15, please amend as follows:

w --An alternate technique for fabricating the conductor patterns and vias of a flex circuit package substrate using an embossing tool includes the following steps. Securing a metal matrix with embossed studs and/or conductor patterns fabricated from known technology such as electroforming or etching, coating the raised areas with a loosely held thin film of copper, transferring the copper film to a dielectric film using heat and pressure, physically removing the matrix, and subsequently plating the appropriate thickness of copper over the thin film of copper. The process is repeated on the second surface having a pattern of solder ball contact pads aligned to the preformed vias. The embossed-film is plated ~~plating~~ with copper from both sides, using the transferred metal as the seed layer.--

In the paragraph bridging pages 16 and 17 of the specification, please amend as follows:

w ~~A schematic drawing of the tool~~ Schematic drawings of the tools for side one is given in Figure 7. In Figure 7, raised areas for the conductor pattern 701, the via punches 702 and pad sites 703 are coated with a thin layer of copper. The base material 700 of the embossing tool is a metallic film. In similar manner, an embossing tool for the second side of the flex circuit includes raised ~~the~~ solder ball contact pads, interconnections to vias and vias coated with a thin film of copper.--